

Chip on Board

DM60M-H MULTI DIE BONDER

KXF-393D

It supports various type of substrate and realizes high-efficiency production with high-speed bonding by dividing processes.



Model name	DM60M-H
Model No.	KXF-393D
Cycle time ※1	0.8 s /cycle (dry cycle)
Bonding accuracy	± 50 μm [option: ± 10 μm ※2]
Substrate dimensions	L 50 mm × W 15 mm to L 310 mm × W 140 mm [option: L 50 mm × W 15 mm to L 310 mm × W 90 mm ※2]
Die size	L 0.9 mm × W 0.9 mm to L 12.0 mm × W 12.0 mm [option: L 0.3 mm × W 0.3 mm to L 25.4 mm × W 25.4 mm]
Die type	Max. 6 types [option: 8 types]
Die supply method	Max. 8 inch wafer/tray
Electric source	Triple phase AC 200 V ± 10 V, 5.2 kVA
Pneumatic source	440 kPa, 50 L/min [Standard]
Dimensions	W 1 800 mm × D 1 650 mm × H 1 520 mm
Mass	1 500 kg

※1: Values such as cycle time, bonding accuracy may vary depending on operational conditions.

※2: When placed with correction through recognition.

※Please refer to the specifications on details.

High-efficiency production

The eight-nozzle automatic switching method is used for the bonding head, and up to eight different dies can be bonded at a time without exchanges, which realizes efficient production.



Bonding heads



Both wafers and trays can be used

Flexible production

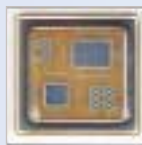
This versatile machine accepts virtually any type of substrate - such as strip-shaped substrates, long substrates, individual substrates on a carrier, or flexible substrates.



Electronic products



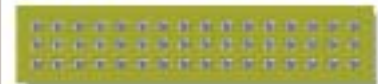
Devices



Substrates



Glass epoxy substrate



Flexible tape

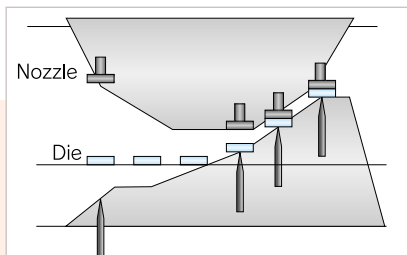


Carrier (courtesy of AUER)



High-quality production

The damage-free die pick-up, the digitally-controlled loading, and the scrub function to improve resin wettability all contribute to high-quality production.



Damage-free die pick up by simultaneous ascend operation control



Bonding table

⚠ Safety Cautions

To ensure safety when using this equipment, all work should be performed according to that as stated in the separate Operating Instructions. Read your operating instructions manual thoroughly.

<http://panasonic.co.jp/pfsc/en/>

Inquiries...

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